

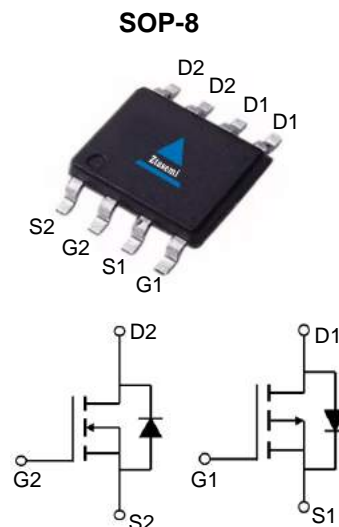
Features

- N and P-Channel
- High power and current handing capability
- Lead free product is acquired
- Surface mount package

V_{DS}	30	V
$R_{DS(on),TYP@ V_{GS}=10V}$	18	m Ω
$R_{DS(on),TYP@ V_{GS}=4.5V}$	22	m Ω
I_D	7	A



Part ID	Package Type	Marking	Packing
ZT4606	SOP-8	ZT4606	4000pcs/reel



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	N-Ch	P-Ch	Unit	
Common Ratings ($T_c=25^\circ\text{C}$ Unless Otherwise Noted)					
V_{GS}	Gate-Source Voltage	± 20	± 20	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	30	-30	V	
T_J	Maximum Junction Temperature	150	150	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	$^\circ\text{C}$	
I_{DM}	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_C = 25^\circ\text{C}$	28	-28	A
Mounted on Large Heat Sink					
I_D	Drain Current-Continuous	$T_C = 25^\circ\text{C}$	7	-7	A
		$T_C = 100^\circ\text{C}$	5.8	-5.8	A
P_D	Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	2	2	W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient (Note 2)		62.5	62.5	$^\circ\text{C/W}$

Electrical Characteristics (T_J=25°C unless otherwise noted) N channel

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J=25°C (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V	--	--	1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.5	3.0	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =7A	--	18	22	mΩ
R _{DS(on)}	Drain-Source On-State Resistance	V _{DS} =4.5V, I _D =4A	--	22	27	mΩ
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated) (Note 4)						
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz	--	592	--	pF
C _{oss}	Output Capacitance		--	130	--	pF
C _{rss}	Reverse Transfer Capacitance		--	91	--	pF
Q _g	Total Gate Charge	V _{DS} =15V, I _b =6A, V _{GS} =10V	--	11	--	nC
Q _{gs}	Gate-Source Charge		--	4.5	--	nC
Q _{gd}	Gate-Drain Charge		--	3.6	--	nC
Switching Characteristics (Note 4)						
T _{d(on)}	Turn-on Delay Time	V _{DD} =15V, R _L =2.5Ω, R _G =3.0Ω, V _{GS} =10V	--	4	--	ns
T _r	Turn-on Rise Time		--	8	--	ns
T _{d(off)}	Turn-Off Delay Time		--	31	--	ns
T _f	Turn-Off Fall Time		--	4	--	ns
Source- Drain Diode Characteristics @ T_J = 25°C (unless otherwise stated)						
I _{SD}	Source-Drain Current (Body Diode)		--	--	7	A
V _{SD}	Forward on voltage (Note 3)	I _S =7.0A, V _{GS} =0V	--	--	1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

N- Channel Typical Electrical and Thermal Characteristics (Curves)

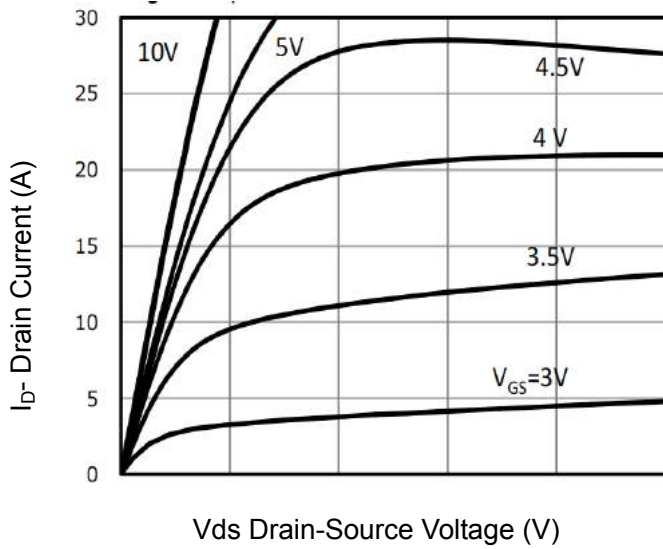


Figure 1 Output Characteristics

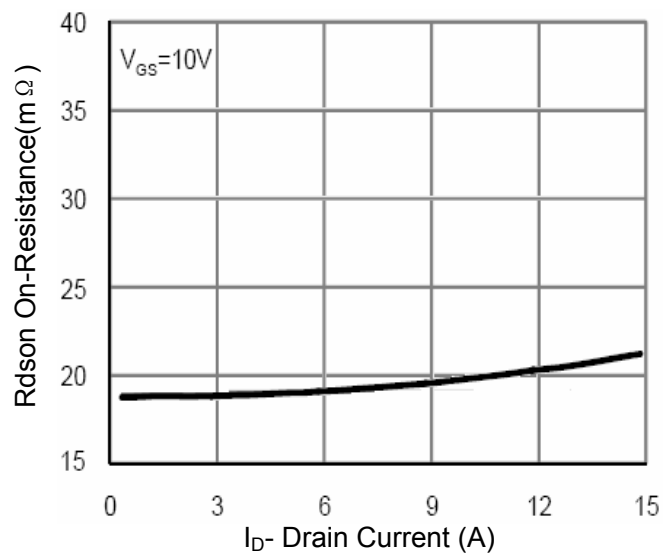


Figure 4 Drain-Source On-Resistance

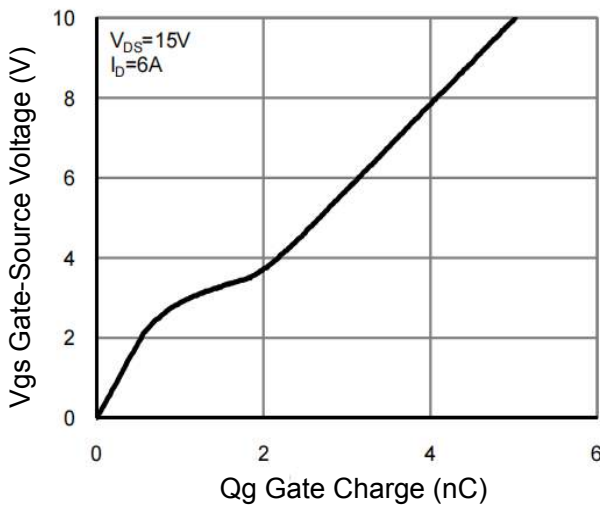


Figure 2 Gate Charge

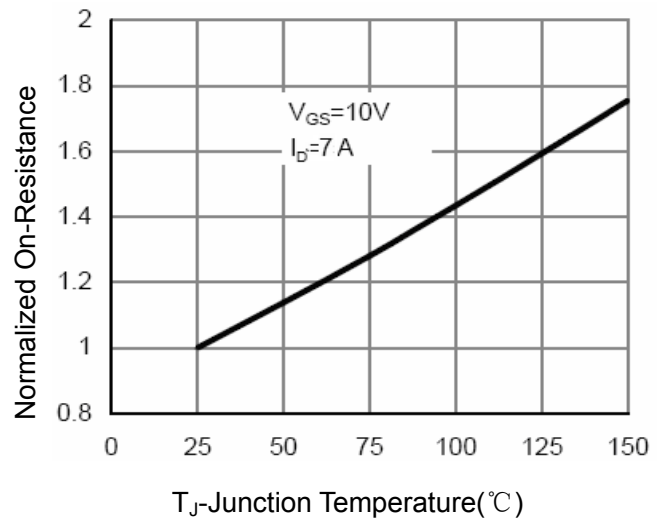


Figure 5 Drain-Source On-Resistance

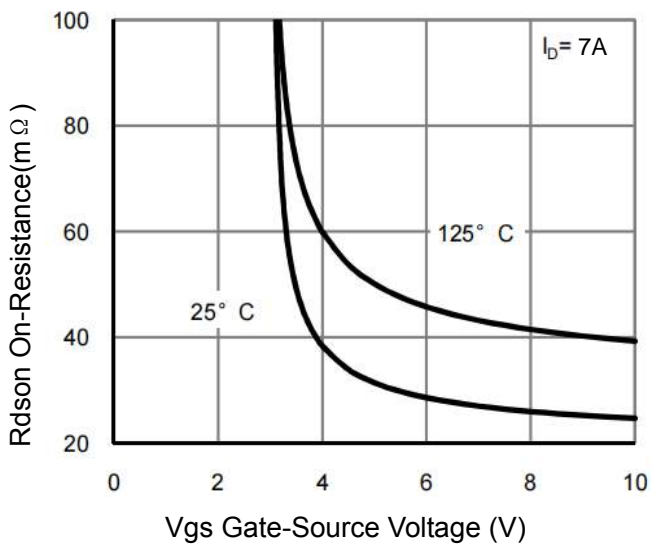


Figure 3 Rdson vs Vgs

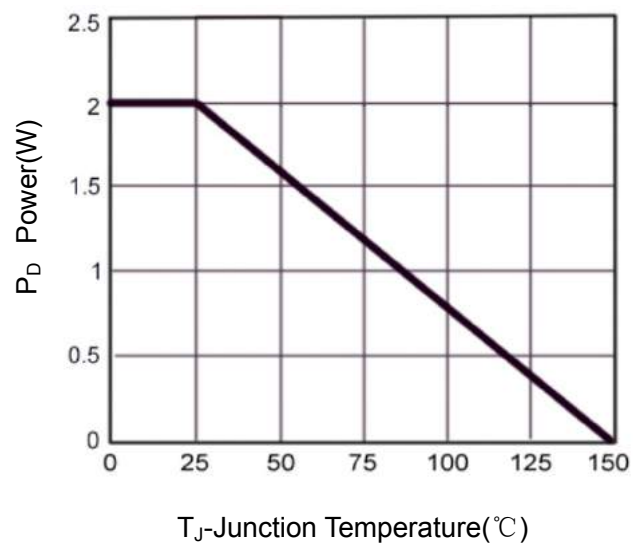


Figure 6 Power Dissipation

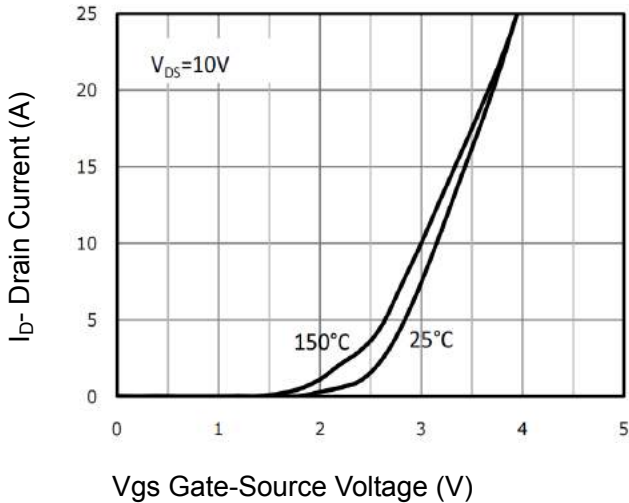


Figure 7 Transfer Characteristics

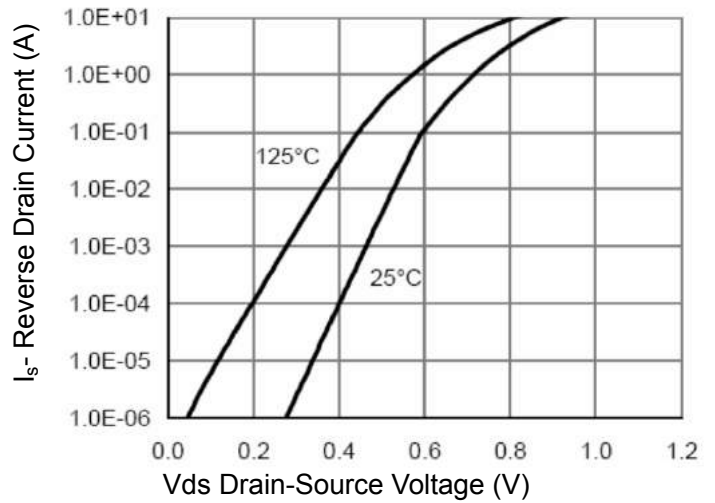


Figure 9 Source- Drain Diode Forward

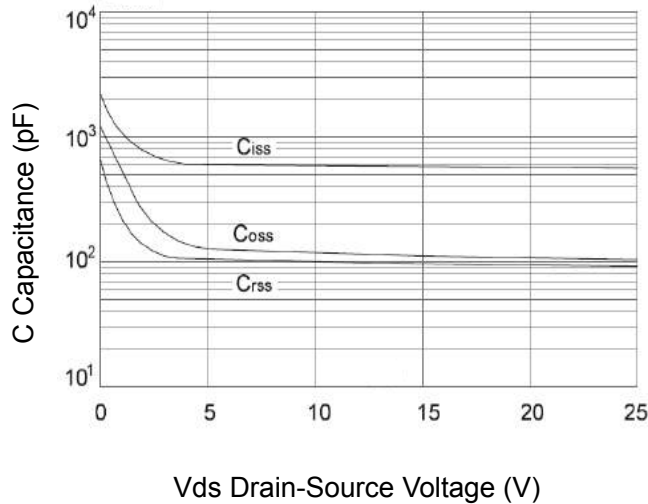


Figure 8 Capacitance vs Vds

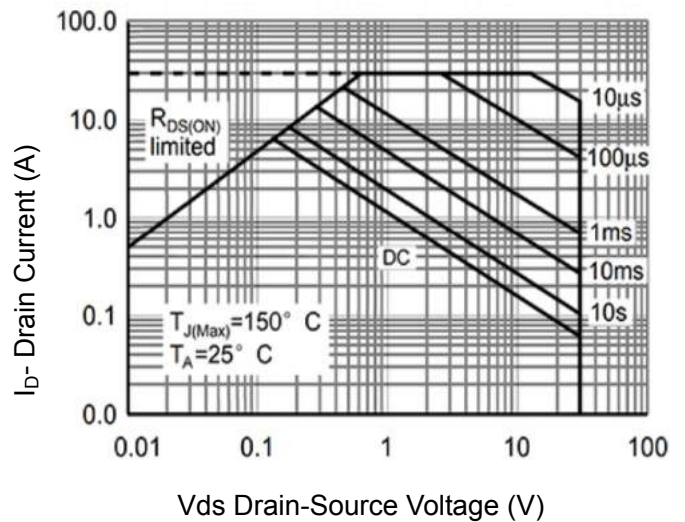


Figure 10 Safe Operation Area

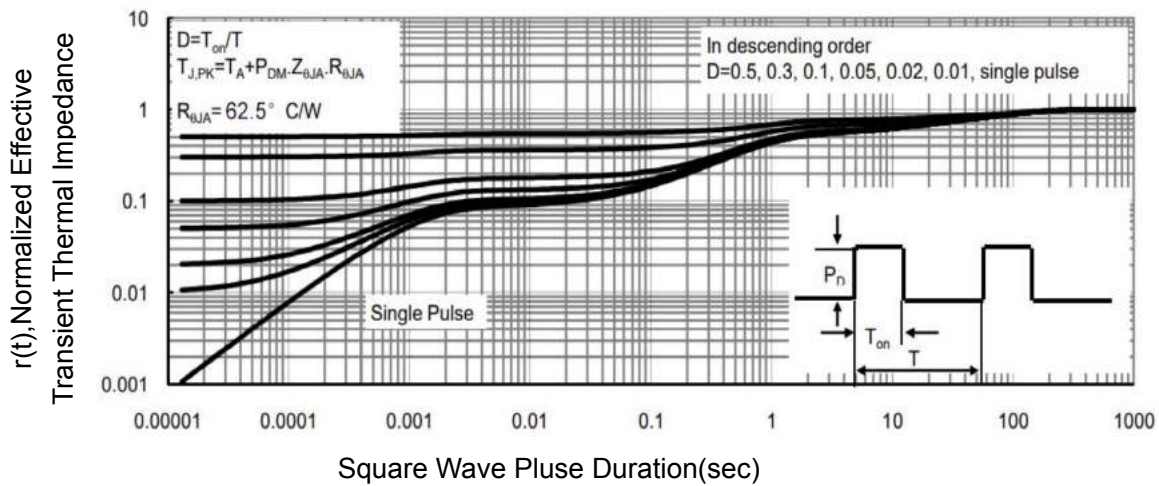
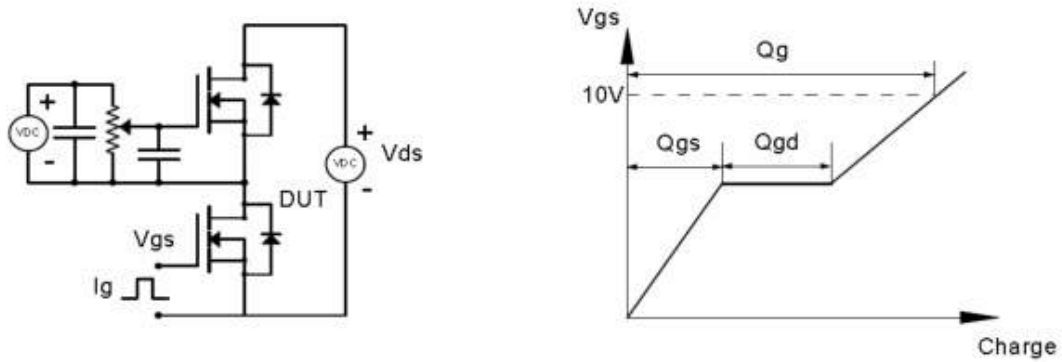


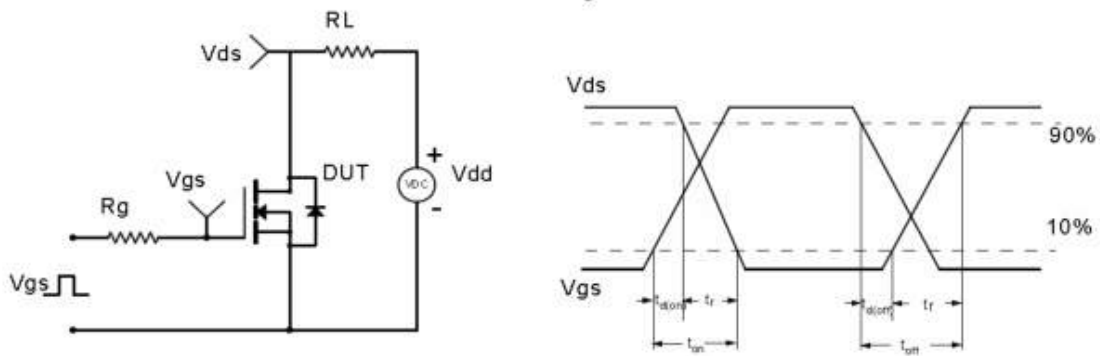
Figure 11 Normalized Maximum Transient Thermal Impedance

Test Circuit & Waveform

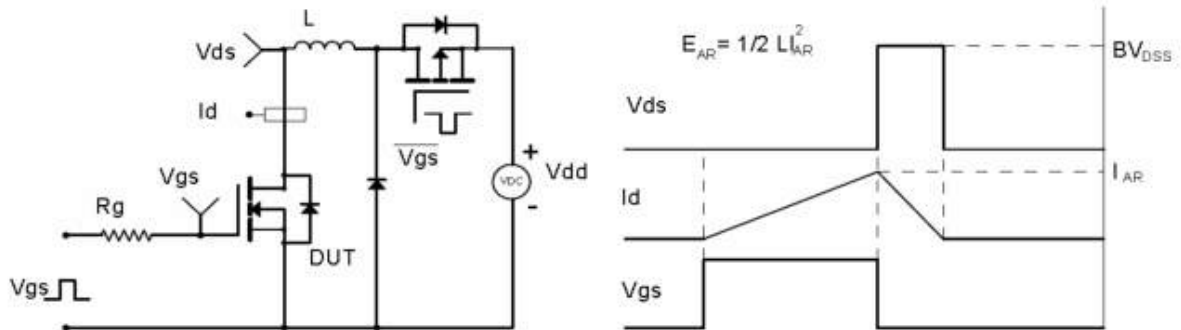
Gate Charge Test Circuit & Waveform



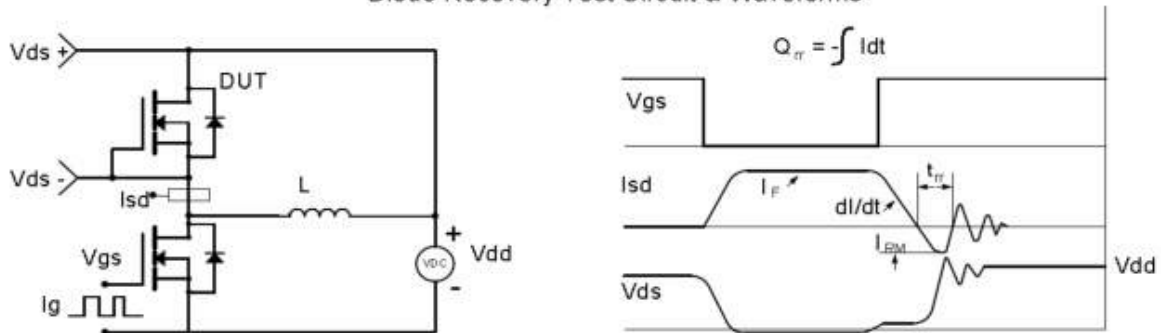
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Electrical Characteristics (T_J=25°C unless otherwise noted) P channel

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J=25°C (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-30	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V	--	--	-1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.1	-1.6	-2.2	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-7A	--	25	32	mΩ
R _{DS(on)}	Drain-Source On-State Resistance	V _{DS} =-4.5V, I _D =-4A	--	32	40	mΩ
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated) (Note 4)						
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	--	933	--	pF
C _{oss}	Output Capacitance		--	126	--	pF
C _{rss}	Reverse Transfer Capacitance		--	103	--	pF
Q _g	Total Gate Charge	V _{DS} =-15V, I _D =-6.5A, V _{GS} =-10V	--	14	--	nC
Q _{gs}	Gate-Source Charge		--	3.3	--	nC
Q _{gd}	Gate-Drain Charge		--	3.2	--	nC
Switching Characteristics (Note 4)						
T _{d(on)}	Turn-on Delay Time	V _{DD} =-15V, R _L =2.3Ω, R _G =6.0Ω, V _{GS} =-10V	--	7.2	--	ns
T _r	Turn-on Rise Time		--	3.8	--	ns
T _{d(off)}	Turn-Off Delay Time		--	2.6	--	ns
T _f	Turn-Off Fall Time		--	3.2	--	ns
Source- Drain Diode Characteristics @ T_J = 25°C (unless otherwise stated)						
I _{SD}	Source-Drain Current (Body Diode)		--	--	-7	A
V _{SD}	Forward on voltage (Note 3)	I _S =-7A, V _{GS} =0V	--	--	-1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

P- Channel Typical Electrical and Thermal Characteristics (Curves)

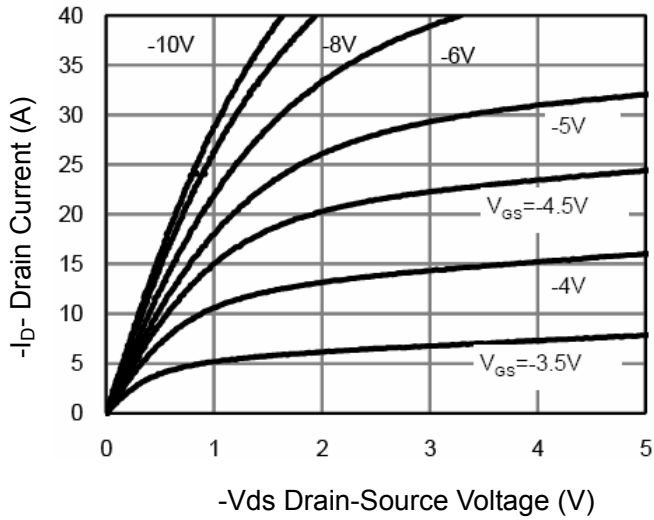


Figure 1 Output Characteristics

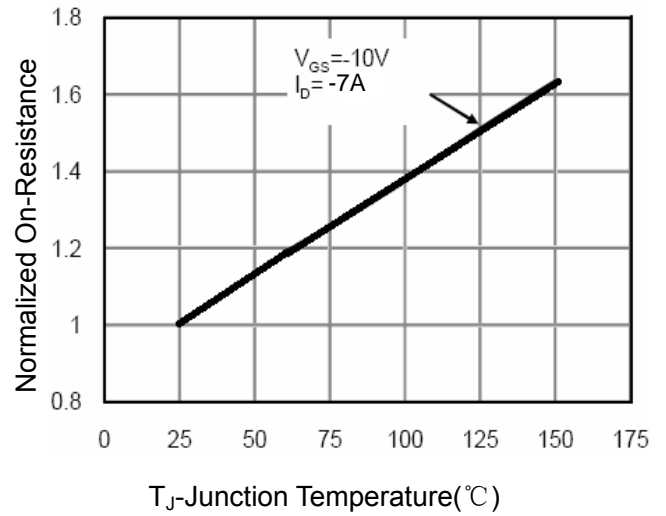


Figure 4 Rdson-Junction Temperature

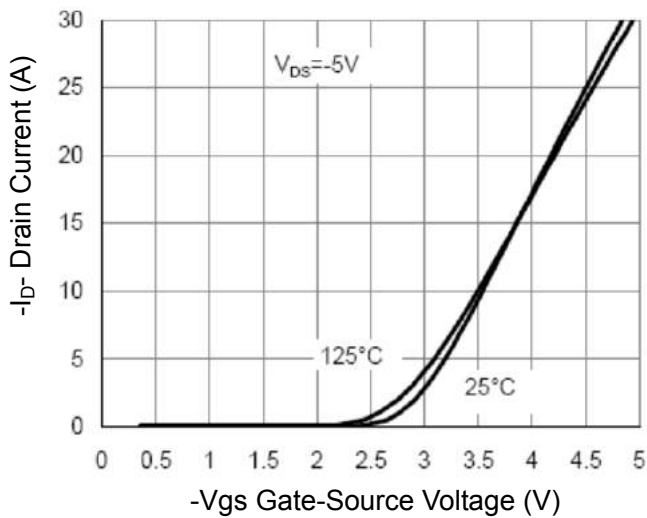


Figure 2 Transfer Characteristics

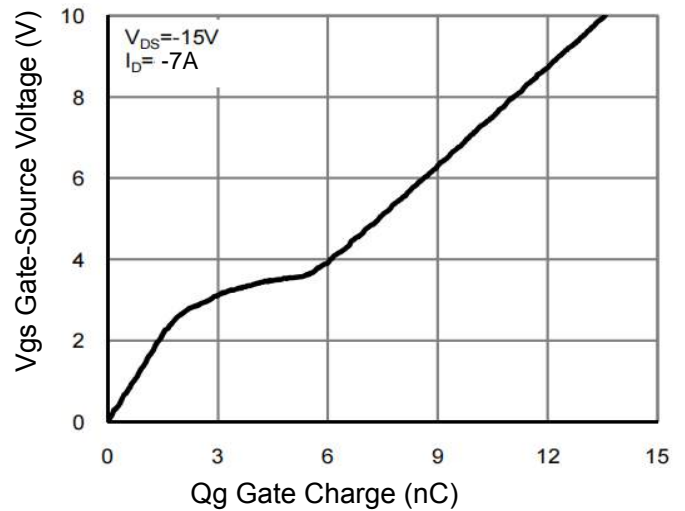


Figure 5 Gate Charge

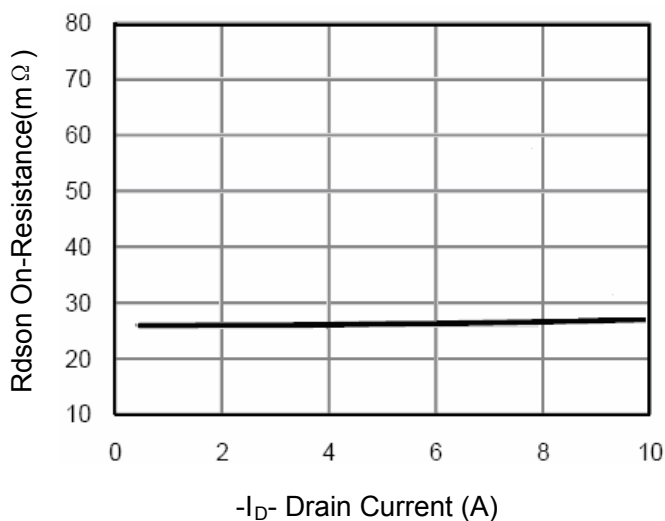


Figure 3 Rdson- Drain Current

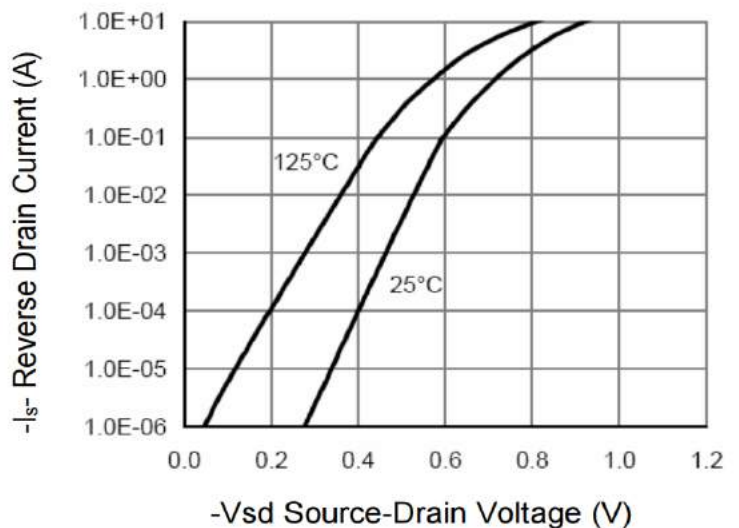


Figure 6 Source- Drain Diode Forward

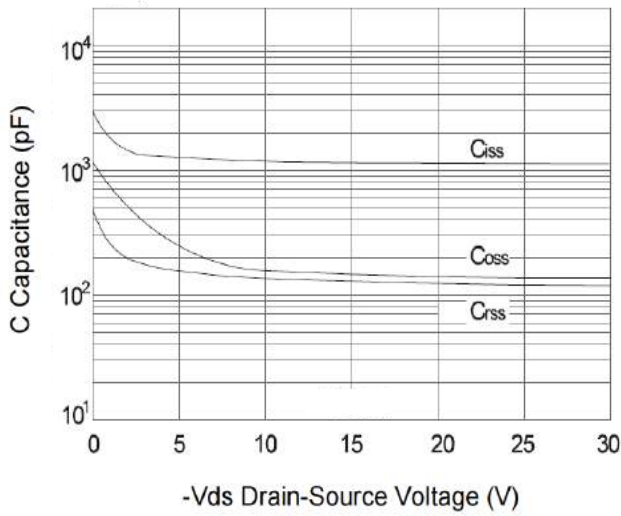


Figure 7 Capacitance vs Vds

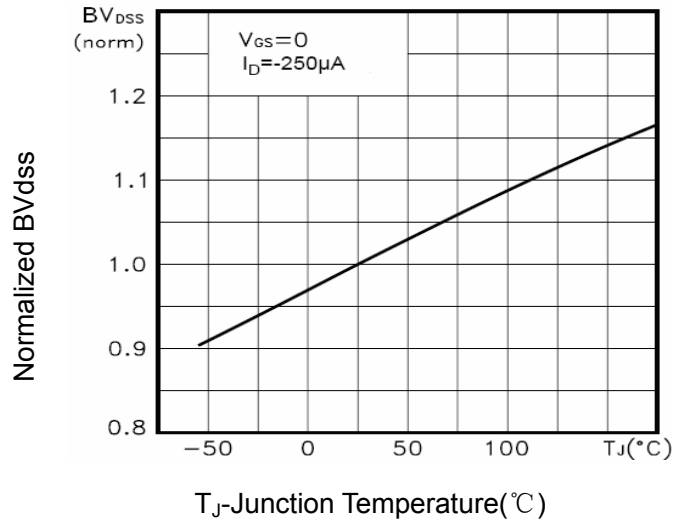


Figure 9 BV_{DSS} vs Junction Temperature

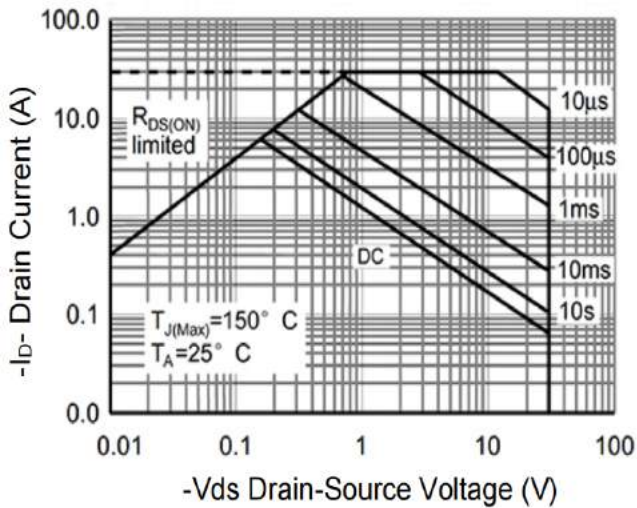


Figure 8 Safe Operation Area

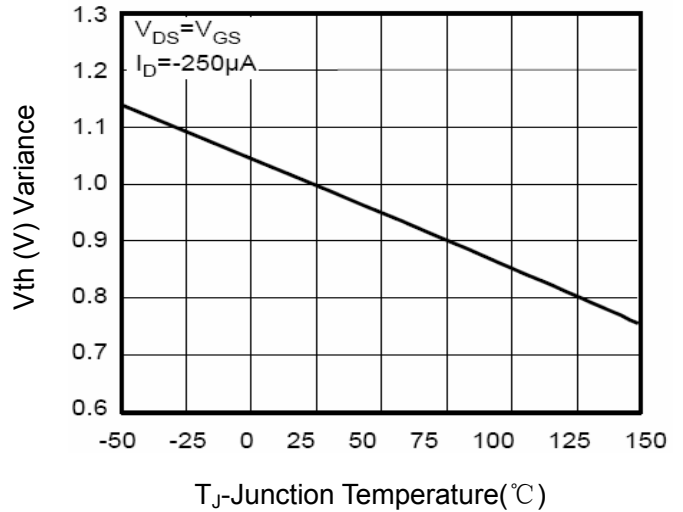


Figure 10 $V_{GS(th)}$ vs Junction Temperature

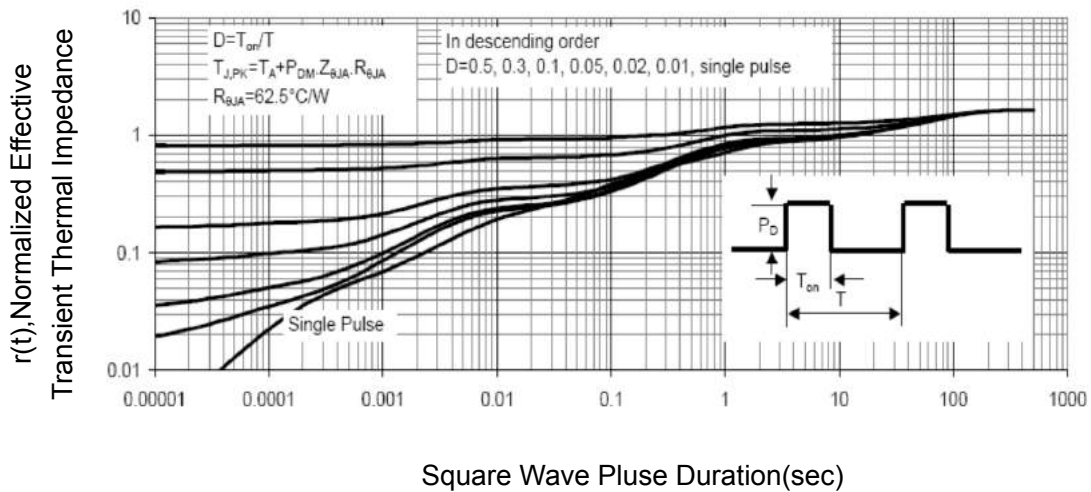
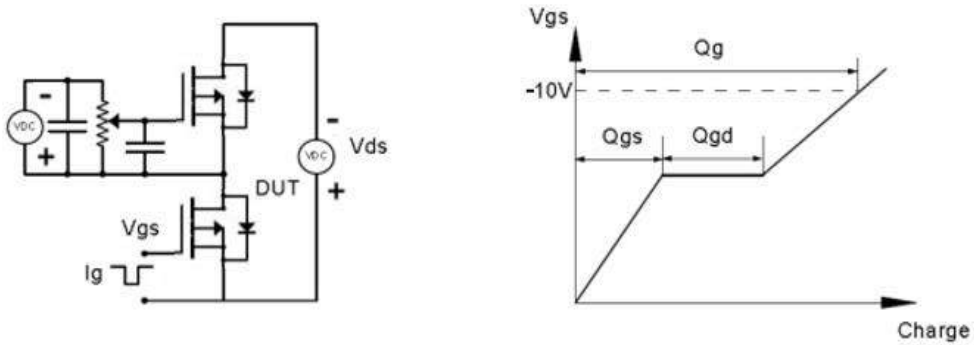


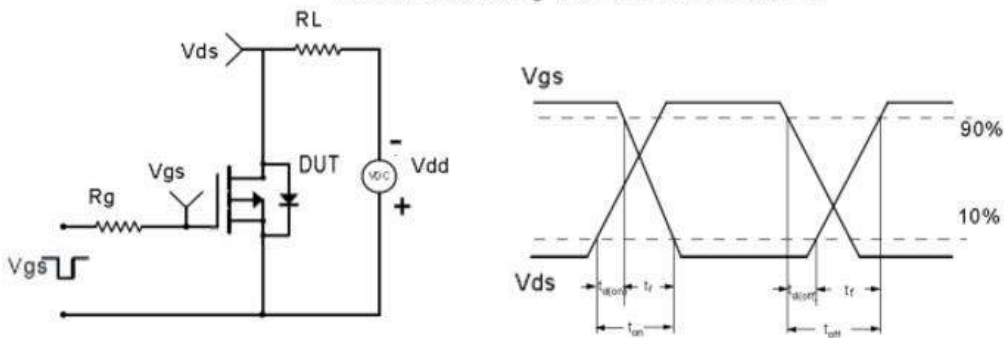
Figure 11 Normalized Maximum Transient Thermal Impedance

Test Circuit & Waveform

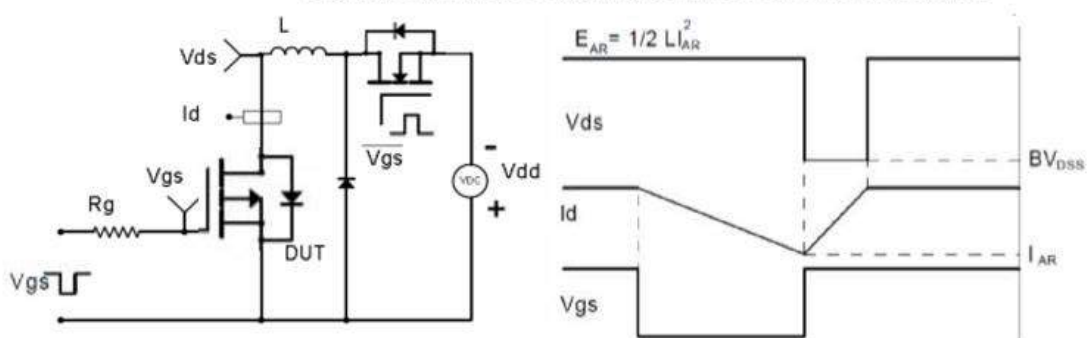
Gate Charge Test Circuit & Waveform



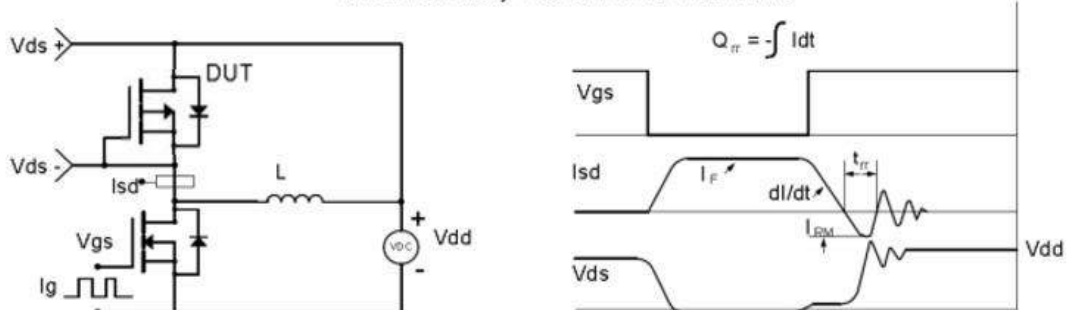
Resistive Switching Test Circuit & Waveforms



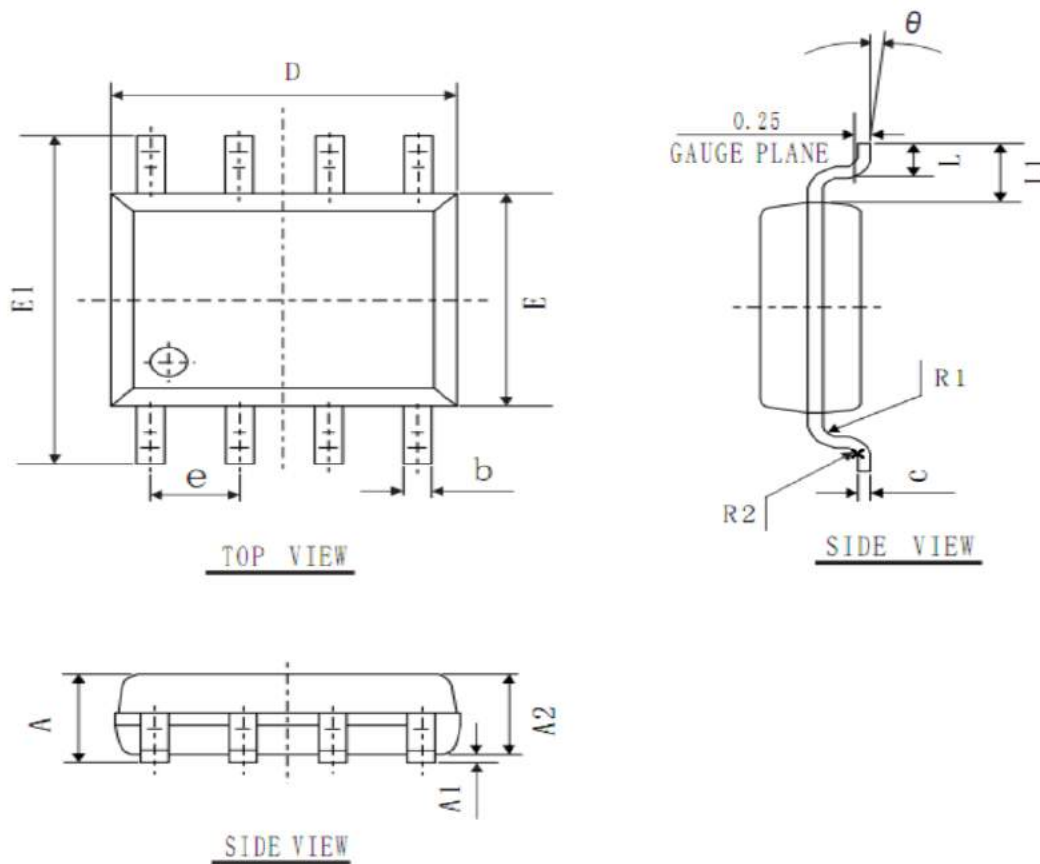
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



SOP-8 Package Information



COMMON DIMENSIONS
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	1.40	1.60	1.80
A1	0.05	0.15	0.25
A2	1.35	1.45	1.55
b	0.30	0.40	0.50
c	0.153	0.203	0.253
D	4.80	4.90	5.00
E	3.80	3.90	4.00
E1	5.80	6.00	6.20
L	0.45	0.70	1.00
θ	2°	4°	6°
L1	1.04 REF		
e	1.27 BSC		
R1	0.07 TYP		
R2	0.07 TYP		

Customer Service

Sales and Service:

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